

16-Bit Registered Transceivers

Features

- I_{off} supports partial-power-down mode operation
- Edge-rate control circuitry for significantly improved noise characteristics
- Typical output skew < 250 ps
- ESD > 2000V
- TSSOP (19.6-mil pitch) and SSOP (25-mil pitch) packages
- Industrial temperature range of -40°C to $+85^{\circ}\text{C}$
- $V_{CC} = 5\text{V} \pm 10\%$

CY74FCT16652T Features:

- 64 mA sink current, 32 mA source current
- Typical V_{OLP} (ground bounce) < 1.0V at $V_{CC} = 5\text{V}$, $T_A = 25^{\circ}\text{C}$

CY74FCT162652T Features:

- Balanced 24 mA output drivers
- Reduced system switching noise
- Typical V_{OLP} (ground bounce) < 0.6V at $V_{CC} = 5\text{V}$, $T_A = 25^{\circ}\text{C}$

Functional Description

These 16-bit, high-speed, low-power, registered transceivers that are organized as two independent 8-bit bus transceivers with three-state D-type registers and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal storage registers. OEAB and OEBA control pins are provided to control the transceiver functions. SAB and SBA control pins are provided to select either real-time or stored data transfer.

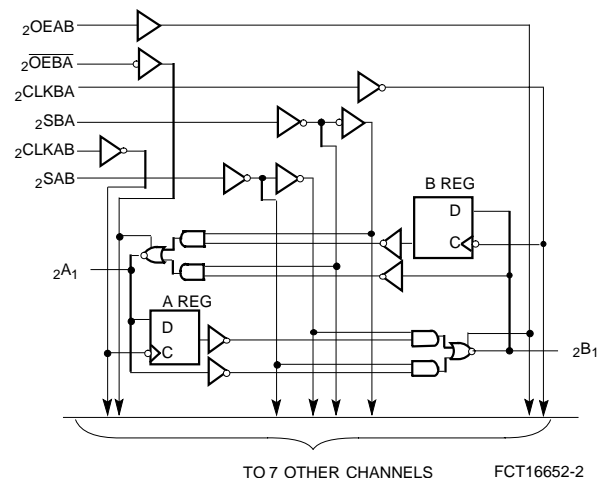
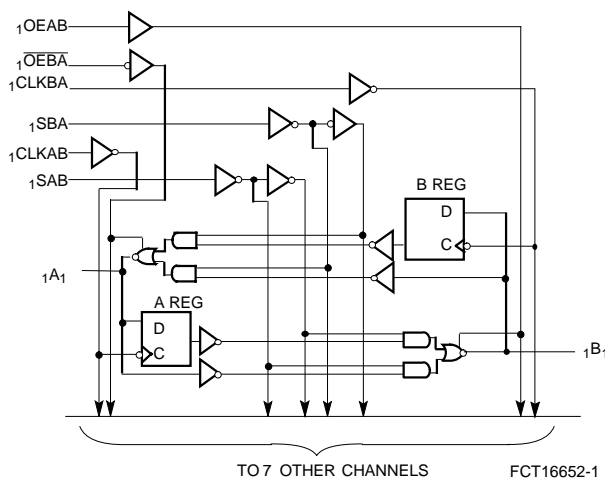
Data on the A or B data bus, or both, can be stored in the internal D flip-flops by LOW-to-HIGH transitions at the appropriate clock pins (CLKAB or CLKBA), regardless of the select or enable control pins. When SAB and SBA are in the real-time transfer mode, it is also possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and OEBA. In this configuration, each output reinforces its input. Thus, when all other data sources to the two sets of bus lines are at high impedance, each set of bus lines will remain at its last state.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The CY74FCT16652T is ideally suited for driving high-capacitance loads and low-impedance backplanes.

The CY74FCT162652T has 24-mA balanced output drivers with current-limiting resistors in the outputs. This reduces the need for external terminating resistors and provides for minimal undershoot and reduced ground bounce. The CY74FCT162652T is ideal for driving transmission lines.

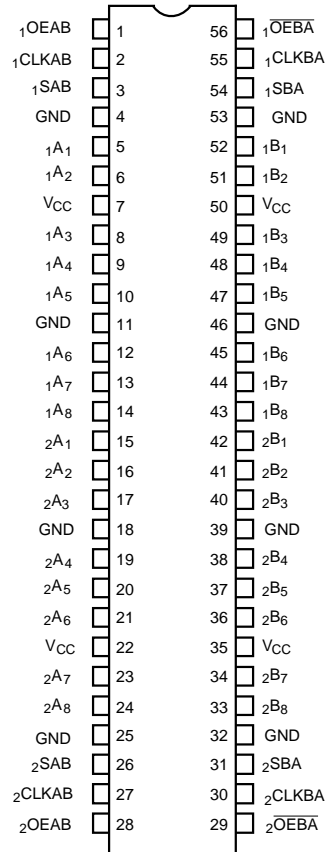
Logic Block Diagrams



Pin Configuration

SSOP/TSSOP

Top View



FCT16652-3

Pin Description

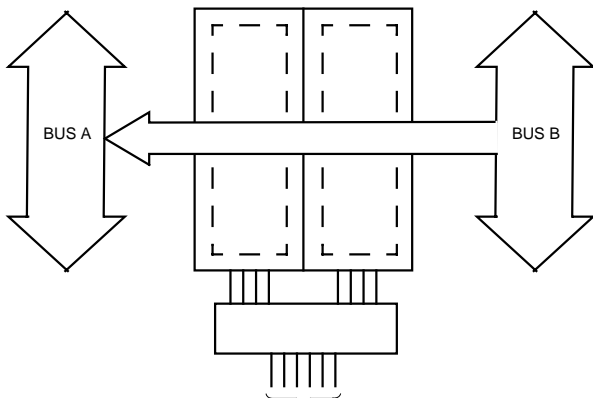
Name	Description
A	Data Register A Inputs Data Register B Outputs
B	Data Register B Inputs Data Register A Outputs
CLKAB, CLKBA	Clock Pulse Inputs
SAB, SBA	Output Data Source Select Inputs
OEAB, OEBA	Output Enable Inputs

Function Table^[1]

Inputs						Data I/O ^[2]		Operation or Function
OEAB	OEBA	CLKAB	CLKBA	SAB	SBA	A	B	
L L	H H	H or L ┐	H or L ┐	X X	X X	Input	Input	Isolation Store A and B Data
X H	H H	┐ ┐	H or L ┐	X X ^[3]	X X	Input Input	Unspecified ^[2] Output	Store A, Hold B Store A in Both Registers
L L	X L	H or L ┐	┐ ┐	X X	X X ^[3]	Unspecified ^[2]	Input Input	Hold A, Store B Store B in both Registers
L L	L L	X X	X H or L	X X	L H	Output	Input	Real Time B Data to A Bus Stored B Data to A Bus
H H	H H	X H or L	X X	L H	X X	Input	Output	Real Time A Data to B Bus Stored A Data to B Bus
H	L	H or L	H or L	H	H	Output	Output	Stored A Data to B Bus and Stored B Data to A Bus

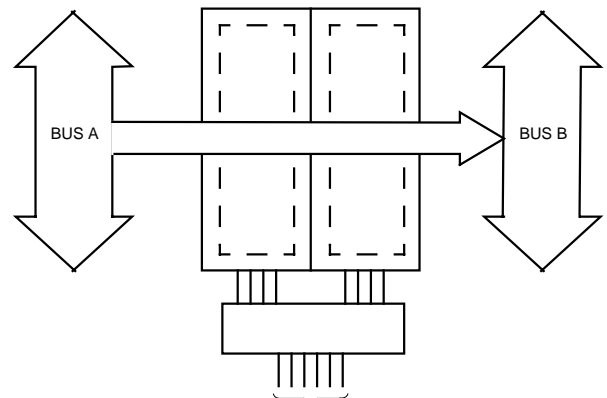
Notes:

- H = HIGH Voltage Level
L = LOW Voltage Level
X = Don't Care
┐ = LOW-to-HIGH Transition
- The data output functions may be enabled or disabled by various signals at the OEAB or OEBA inputs. Data input functions are always enabled, i.e., data at the bus pins will be stored on every LOW-to-HIGH transition on the clock inputs.
- Select control=L; clocks can occur simultaneously.
Select control=H; clocks must be staggered to load both registers.



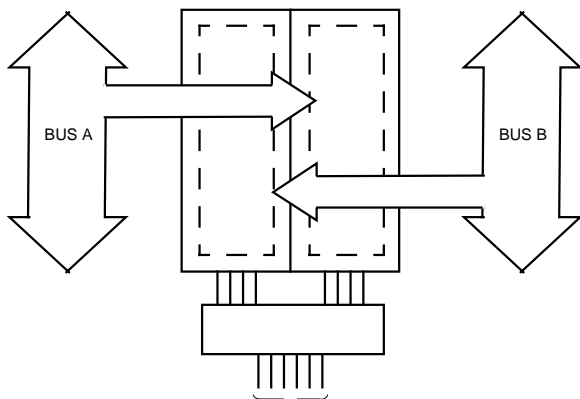
OEAB L $\overline{\text{OEBA}}$ L CLKAB X CLKBA X SAB X SBA L

**Real-Time Transfer
Bus B to Bus A**



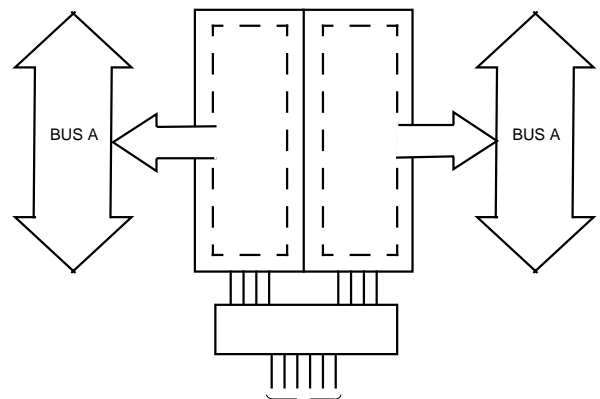
OEAB H $\overline{\text{OEBA}}$ L CLKAB X CLKBA X SAB L SBA X

**Real-Time Transfer
Bus A to Bus B**



OEAB X L L $\overline{\text{OEBA}}$ H X H CLKAB \downarrow X \downarrow CLKBA X \downarrow SAB X X X SBA X X X

**Storage from
A and/or B**



OEAB H $\overline{\text{OEBA}}$ L CLKAB H or L CLKBA H or L SAB H SBA H

**Transfer Stored Data
to A and/or B**

Maximum Ratings^[4]

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage TemperatureCom'I -55°C to +125°C

Ambient Temperature with Power AppliedCom'I -55°C to +125°C

DC Input Voltage-0.5V to +7.0V

DC Output Voltage-0.5V to +7.0V

DC Output Current (Maximum Sink Current/Pin)-60 to +120 mA

Power Dissipation 1.0W

Static Discharge Voltage.....>2001V (per MIL-STD-883, Method 3015)

Operating Range

Range	Ambient Temperature	V _{CC}
Industrial	-40°C to +85°C	5V ± 10%

Note:

- Stresses greater than those listed under Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

DC Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions ^[5]	Min.	Typ. ^[6]	Max.	Unit
V _{IH}	Input HIGH Voltage	Logic HIGH Level	2.0			V
V _{IL}	Input LOW Voltage	Logic LOW Level			0.8	V
V _H	Input Hysteresis			100		mV
V _{IK}	Input Clamp Diode Voltage	V _{CC} =Min., I _{IN} =-18 mA		-0.7	-1.2	V
I _{IH}	Input HIGH Current	V _{CC} =Max., V _I =V _{CC}			±1	μA
I _{IL}	Input LOW Current	V _{CC} =Max., V _I =GND			±1	μA
I _{OZH}	High Impedance Output Current (Three-State Output pins)	V _{CC} =Max., V _{OUT} =2.7V			±1	μA
I _{OZL}	High Impedance Output Current (Three-State Output pins)	V _{CC} =Max., V _{OUT} =0.5V			±1	μA
I _{OS}	Short Circuit Current ^[8]	V _{CC} =Max., V _{OUT} =GND	-80	-140	-200	mA
I _O	Output Drive Current ^[8]	V _{CC} =Max., V _{OUT} =2.5V	-50		-180	mA
I _{OFF}	Power-Off Disable	V _{CC} =0V, V _{OUT} ≤4.5V ^[7]			±1	μA

Output Drive Characteristics for CY74FCT16652T

Parameter	Description	Test Conditions ^[5]	Min.	Typ. ^[6]	Max.	Unit
V _{OH}	Output HIGH Voltage	V _{CC} =Min., I _{OH} =-3 mA	2.5	3.5		V
		V _{CC} =Min., I _{OH} =-15 mA	2.4	3.5		
		V _{CC} =Min., I _{OH} =-32 mA	2.0	3.0		
V _{OL}	Output LOW Voltage	V _{CC} =Min., I _{OL} =64 mA		0.2	0.55	V

Output Drive Characteristics for CY74FCT162652T

Parameter	Description	Test Conditions ^[5]	Min.	Typ. ^[6]	Max.	Unit
I _{ODL}	Output LOW Current ^[8]	V _{CC} =5V, V _{IN} =V _{IH} or V _{IL} , V _{OUT} =1.5V	60	115	150	mA
I _{ODH}	Output HIGH Current ^[8]	V _{CC} =5V, V _{IN} =V _{IH} or V _{IL} , V _{OUT} =1.5V	-60	-115	-150	mA
V _{OH}	Output HIGH Voltage	V _{CC} =Min., I _{OH} =-24 mA	2.4	3.3		V
V _{OL}	Output LOW Voltage	V _{CC} =Min., I _{OL} =24 mA		0.3	0.55	V

Capacitance (T_A = +25°C, f = 1.0 MHz)

Parameter	Description ^[10]	Test Conditions	Typ.	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 0V	4.5	6.0	pF
C _{OUT}	Output Capacitance	V _{OUT} = 0V	5.5	8.0	pF

Notes:

5. For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type.
6. Typical values are at V_{CC}=5.0V, +25°C ambient.
7. Tested at T_A= +25°C.
8. Not more than one output should be tested at one time. Duration of the test should not exceed one second.
9. Duration of the condition cannot exceed one second.
10. This parameter is measured at characterization but not tested.

Power Supply Characteristics

Param.	Description	Test Conditions ^[11]		Min.	Typ. ^[12]	Max.	Unit
I _{CC}	Quiescent Power Supply Current	V _{CC} =Max.	V _{IN} ≤0.2V V _{IN} ≥V _{CC} -0.2V	—	5	500	μA
ΔI _{CC}	Quiescent Power Supply Current TTL Inputs HIGH	V _{CC} = Max. V _{IN} =3.4V ^[13]		—	0.5	1.5	mA
I _{CCD}	Dynamic Power Supply Current ^[14]	V _{CC} =Max. Outputs Open OEAB=OEAB=GND One Input Toggling 50% Duty Cycle	V _{IN} =V _{CC} or V _{IN} =GND	—	75	120	μA/ MHz
I _C	Total Power Supply Current ^[15]	V _{CC} =Max. Outputs Open f _o =10 MHz (CLKBA) 50% Duty Cycle OEAB=OEAB=GND One-Bit Toggling f ₁ =5 MHz 50% Duty Cycle	V _{IN} =V _{CC} or V _{IN} =GND	—	0.8	1.7	mA
			V _{IN} =3.4V or V _{IN} =GND	—	1.3	3.2	mA
		V _{CC} =Max. Outputs Open f _o =10 MHz (CLKBA) 50% Duty Cycle OEAB=OEAB=GND Sixteen Bits Toggling f ₁ =2.5 MHz 50% Duty Cycle	V _{IN} =V _{CC} or V _{IN} =GND	—	3.8	6.5 ^[16]	mA
			V _{IN} =3.4V or V _{IN} =GND	—	8.3	20.0 ^[16]	mA

Notes:

11. For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type.
12. Typical values are at V_{CC}=5.0V +25° ambient.
13. Per TTL driven input (V_{IN}=3.4V); all other inputs at V_{CC} or GND.
14. This parameter is not directly testable, but is derived for use in Total Power Supply calculations.
15. I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}
I_C = I_{CC} + ΔI_{CC}D_HN_T + I_{CCD}(f_o/2 + f₁N₁)
I_{CC} = Quiescent Current with CMOS input levels
ΔI_{CC} = Power Supply Current for a TTL HIGH input (V_{IN}=3.4V)
D_H = Duty Cycle for TTL inputs HIGH
N_T = Number of TTL inputs at D_H
I_{CCD} = Dynamic Current caused by an input transition pair (HLH or LHL)
f_o = Clock frequency for registered devices, otherwise zero
f₁ = Input signal frequency
N₁ = Number of inputs changing at f₁
All currents are in milliamps and all frequencies are in megahertz.
16. Values for these conditions are examples of the I_{CC} formula. These limits are specified but not tested.

Switching Characteristics Over the Operating Range^[17]

Parameter	Description	CY74FCT16652AT CY74FCT162652AT		Unit	Fig. No. ^[18]
		Min.	Max.		
t _{PLH} t _{PHL}	Propagation Delay Bus to Bus	1.5	6.3	ns	1, 3
t _{PZH} t _{PHL}	Output Enable Time OEAB or \overline{OEBA} to Bus	1.5	9.8	ns	1, 7, 8
t _{PHZ} t _{PLZ}	Output Disable Time OEAB or \overline{OEBA} to Bus	1.5	6.3	ns	1, 7, 8
t _{PLH} t _{PHL}	Propagation Delay Clock to Bus	1.5	6.3	ns	1, 5
t _{PLH} t _{PHL}	Propagation Delay SBA or SAB to Bus	1.5	7.7	ns	1, 5
t _{SU}	Set-Up time HIGH or LOW Bus to Clock	2.0	—	ns	4
t _H	Hold Time HIGH or LOW Bus to Clock	1.5	—	ns	4
t _W	Clock Pulse Width HIGH or LOW	5.0	—	ns	5
t _{SK(O)}	Output Skew ^[19]	—	0.5	ns	

Parameter	Description	CY74FCT16652CT CY74FCT162652CT		Unit	Fig. No. ^[18]
		Min.	Max.		
t _{PLH} t _{PHL}	Propagation Delay Bus to Bus	1.5	5.4	ns	1, 3
t _{PZH} t _{PHL}	Output Enable Time OEAB or \overline{OEBA} to Bus	1.5	7.8	ns	1, 7, 8
t _{PHZ} t _{PLZ}	Output Disable Time OEAB or \overline{OEBA} to Bus	1.5	6.3	ns	1, 7, 8
t _{PLH} t _{PHL}	Propagation Delay Clock to Bus	1.5	5.7	ns	1, 5
t _{PLH} t _{PHL}	Propagation Delay SBA or SAB to Bus	1.5	6.2	ns	1, 5
t _{SU}	Set-Up Time HIGH or LOW Bus to Clock	2.0	—	ns	4
t _H	Hold Time HIGH or LOW Bus to Clock	1.5	—	ns	4
t _W	Clock Pulse Width HIGH or LOW	5.0	—	ns	5
t _{SK(O)}	Output Skew ^[19]	—	0.5	ns	

Notes:

17. Minimum limits are specified, but not tested, on propagation delays.

18. See "Parameter Measurement Information" in the General Information section.

19. Skew between any two outputs of the same package switching in the same direction. This parameter ensured by design.

Ordering Information CY74FCT16652

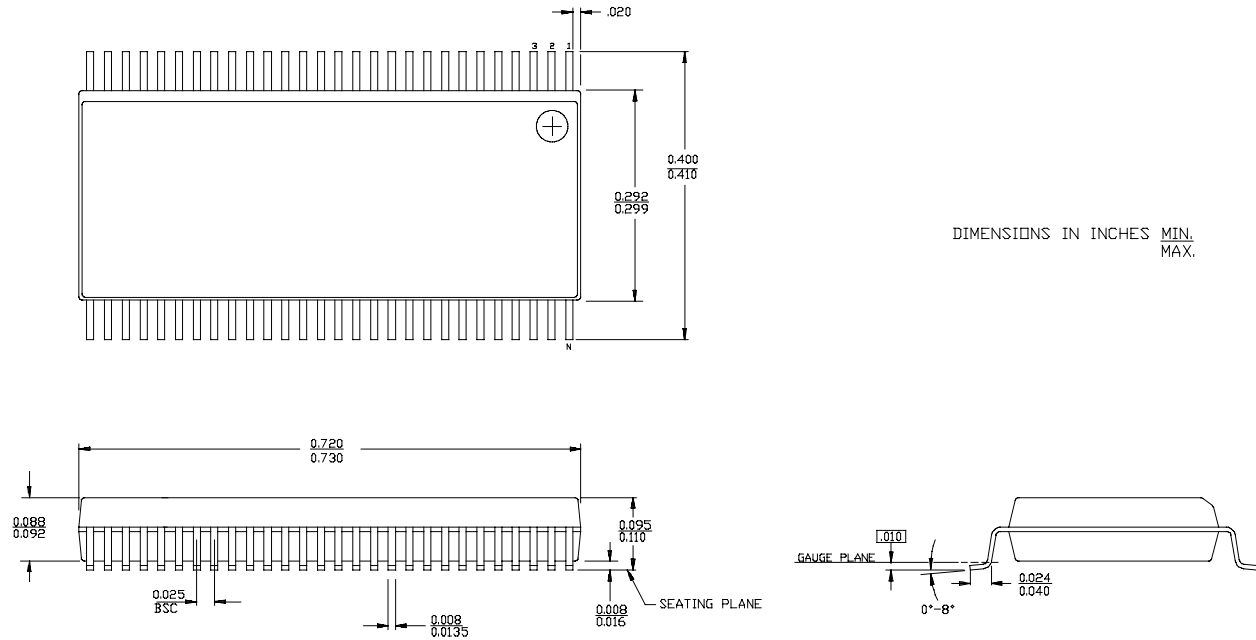
Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
5.4	CY74FCT16652CTPVC/PVCT	O56	56-Lead (300-Mil) SSOP	Industrial
6.3	CY74FCT16652ATPVC/PVCT	O56	56-Lead (300-Mil) SSOP	Industrial

Ordering Information CY74FCT162652

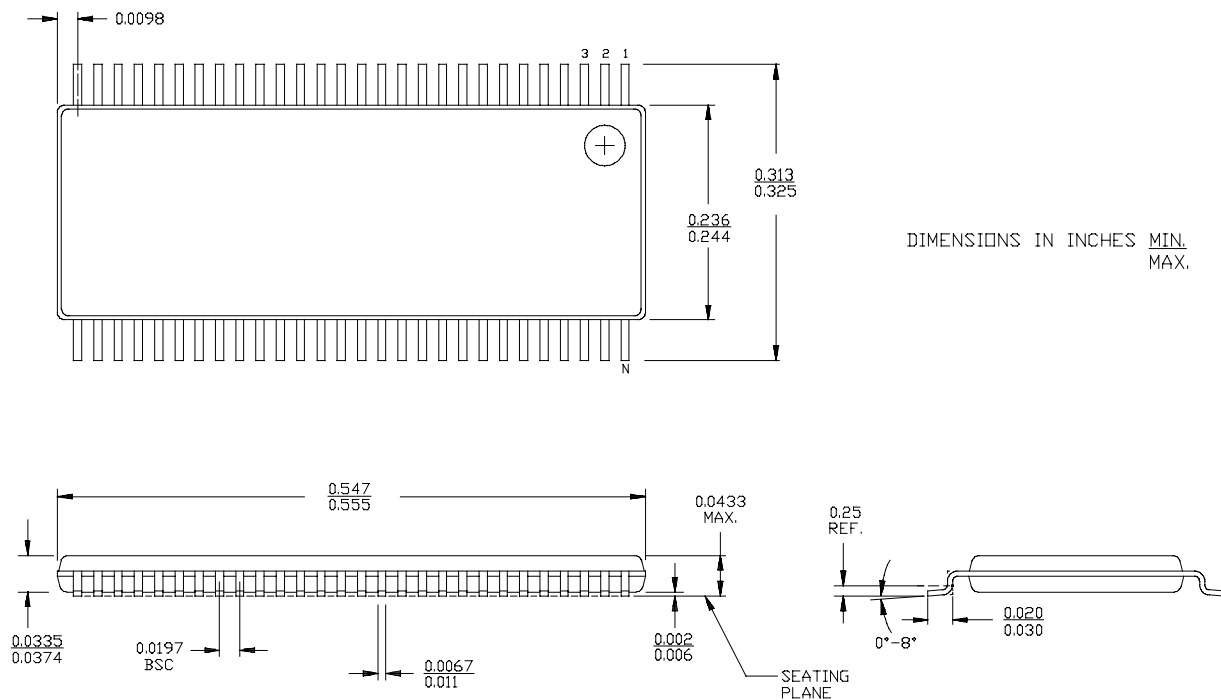
Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
5.4	74FCT162652CTPACT	Z56	56-Lead (240-Mil) TSSOP	Industrial
	CY74FCT162652CTPVC	O56	56-Lead (300-Mil) SSOP	
	74FCT162652CTPVCT	O56	56-Lead (300-Mil) SSOP	
6.3	CY74FCT162652ATPVC	O56	56-Lead (300-Mil) SSOP	Industrial
	74FCT162652ATPVCT	O56	56-Lead (300-Mil) SSOP	

Package Diagrams

56-Lead Shrunken Small Outline Package O56



56-Lead Thin Shrunken Small Outline Package Z56



PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
74FCT162652ATPVCG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT162652A	Samples
74FCT162652ATPVCT	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT162652A	Samples
74FCT162652CTPACT	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT162652C	Samples
74FCT162652ETPACT	OBSOLETE	TSSOP	DGG	56		TBD	Call TI	Call TI	-40 to 85		
74FCT162652ETPVCT	OBSOLETE	SSOP	DL	56		TBD	Call TI	Call TI	-40 to 85		
74FCT16652ATPVCG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT16652A	Samples
74FCT16652CTPVCG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT16652C	Samples
74FCT16652CTPVCTG4	ACTIVE	SSOP	DL	56		TBD	Call TI	Call TI	-40 to 85		Samples
CY74FCT162652ATPVC	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT162652A	Samples
CY74FCT162652ETPAC	OBSOLETE	TSSOP	DGG	56		TBD	Call TI	Call TI	-40 to 85		
CY74FCT162652ETPVC	OBSOLETE	SSOP	DL	56		TBD	Call TI	Call TI	-40 to 85		
CY74FCT16652ATPVC	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT16652A	Samples
CY74FCT16652ATPVCT	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT16652A	Samples
CY74FCT16652CTPVC	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT16652C	Samples
CY74FCT16652ETPAC	OBSOLETE	TSSOP	DGG	56		TBD	Call TI	Call TI	-40 to 85		
CY74FCT16652ETPACT	OBSOLETE	TSSOP	DGG	56		TBD	Call TI	Call TI	-40 to 85		
CY74FCT16652ETPVC	OBSOLETE	SSOP	DL	56		TBD	Call TI	Call TI	-40 to 85		
CY74FCT16652ETPVCT	OBSOLETE	SSOP	DL	56		TBD	Call TI	Call TI	-40 to 85		

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74FCT162652ATPVCT	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1
74FCT162652CTPACT	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
CY74FCT16652ATPVCT	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74FCT162652ATPVCT	SSOP	DL	56	1000	367.0	367.0	55.0
74FCT162652CTPACT	TSSOP	DGG	56	2000	367.0	367.0	45.0
CY74FCT16652ATPVCT	SSOP	DL	56	1000	367.0	367.0	55.0

MECHANICAL DATA

DL (R-PDSO-G56)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.

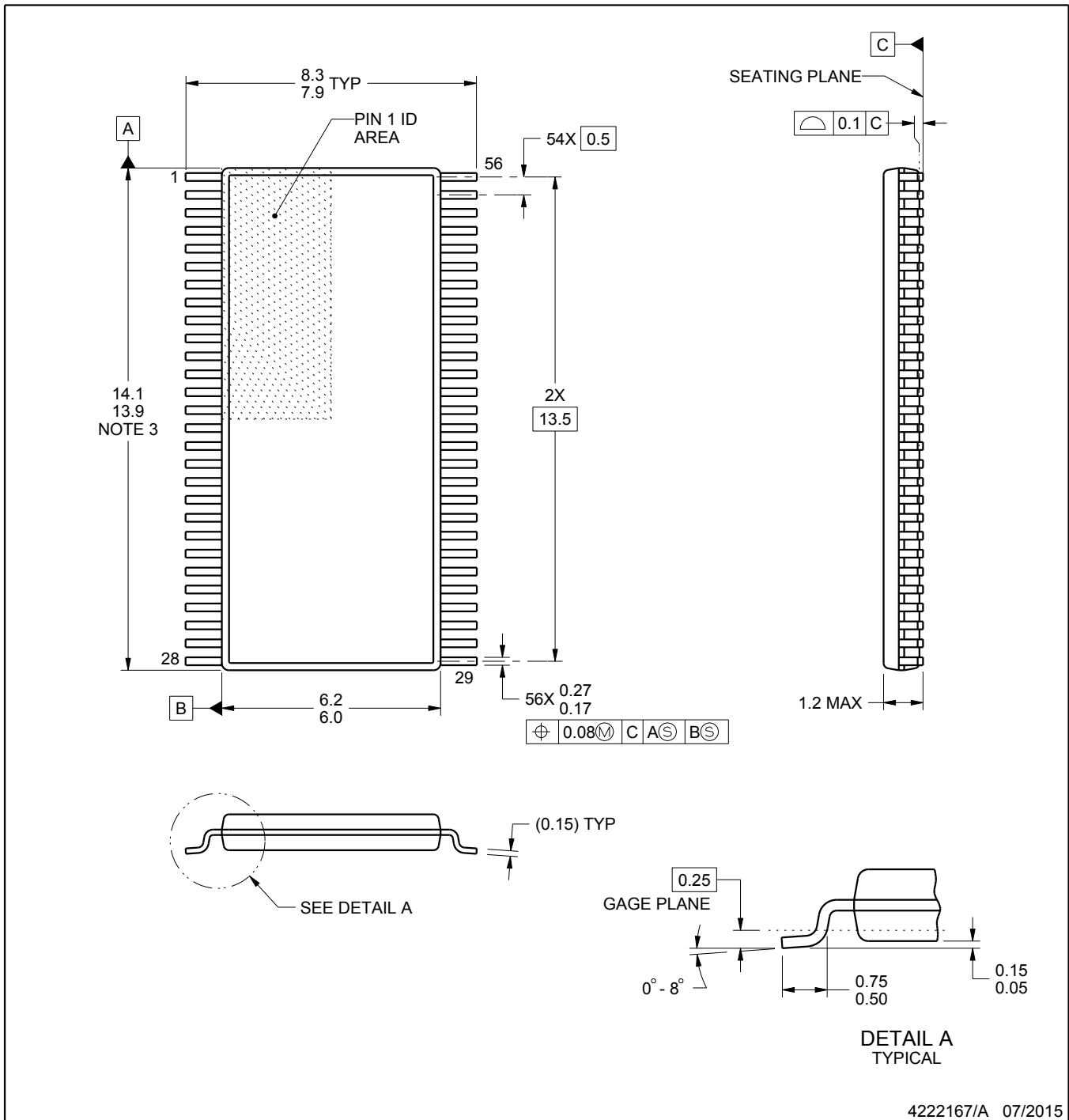
DGG0056A



PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4222167/A 07/2015

NOTES:

- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
- Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

DGG0056A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

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NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DGG0056A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4222167/A 07/2015

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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